ř-	17 1	T	17. A.		
	Number	Hits		DB	Time stamp
1		444	(361/729 or 361/730 or 174/50 or 174/51)	USPAT;	2004/05/25 21:33
			and capacitor	US-PGPUB;	
				EPO; JPO;	
			,	DERWENT;	
		-	'	IBM_TDB	
-		1	"20020020915"	USPĀT;	2004/05/25 14:16
				US-PGPUB	
-		5	59072757.pn. or 09199666.pn. or	JPO	2004/05/25 12:40
			04130453.pn. or 08148595.pn. or		
			07263619.pn.	,	
-		4528	257/787	USPAT;	2004/05/25 14:17
				US-PGPUB;	
				EPO; JPO;	
			*	DERWENT;	
				IBM TDB	
_		368	257/787 and capacitor	USPAT;	2004/05/25 14:17
1		300	2017107 and capacitor	US-PGPUB;	2004/03/23 14.17
				EPO; JPO;	
1			,		•
1	•			DERWENT;	-
		1410	/057/707 am 057/704 am 057/700\	IBM_TDB	2004/05/25 21 55
		1412		USPAT;	2004/05/25 21:30
			capacitor	_US-PGPUB;	
		·	4	EPO; JPO;	'
				DERWENT;	
	ı		· · · · · · · · · · · · · · · · · · ·	IBM_TDB	
-		388		USPAT;	2004/05/25 14:43
1			capacitor and ground with (plane or plate	US-PGPUB;	
		-	or film or layer)	EPO; JPO;	
				DERWENT;	e
				IBM_TDB	
-		114	(257/68 or 257/71 or 257/924) and	USPAT;	2004/05/25 14:58
		, ,	capacitor and ground with (plane or plate	US-PGPUB;	
1			or film or layer)	EPO; JPO;	,
'		-		DERWENT; .	·
				IBM TDB	
P _		. 308	(257/908 or 257/532 or 257/516) and	USPAT;	2004/05/25 17:55
9			capacitor and ground with (plane or plate	US-PGPUB;	
			or film or layer)	EPO; JPO;	
				DERWENT;	*
				IBM TDB	-
· _		149	(257/308 or 257/307 or 257/300) and	USPAT;	2004/05/25 18:16
		149	capacitor and ground with (plane or plate	US-PGPUB;	2301, 33, 23 10.10
			or film or layer).	EPO; JPO;	
			OF FIEM OF Tayer!	DERWENT;	•
				IBM TDB	_
		400	(257/298 or 257/691 or 257/E23.079 or		2004/05/25 19:03
-		493		USPAT;	2004/05/25 19:03
			257/E23.153) and capacitor and ground with	US-PGPUB;	
1			(plane or plate or film or layer)	EPO; JPO;	
-1			· '	DERWENT;	8
		105.5		IBM_TDB	0004/05/05 40 5:
-		12542	(semiconductor or die or chip or IC) and	USPAT;	2004/05/25 19:04
			capacitor and ground with (plane or plate	US-PGPUB;	
			or film or layer)	EPO; JPO;	,
1				DERWENT;	
			·	IBM_TDB	,
-		11453	((semiconductor or die or chip or IC) and	USPAT;	2004/05/25 19:04
			capacitor and ground with (plane or plate	US-PGPUB;	
		. 1	or film or layer)) not (((257/787 or	EPO; JPO;	e a e
1		'	257/724 or 257/723) and capacitor and	DERWENT;	
0			ground with (plane or plate or film or	IBM TDB	
ľ		<u> </u>	layer)) or ((257/68 or 257/71 or 257/924)	_	
			and capacitor and ground with (plane or		
			plate or film or layer)) or ((257/908 or		
			257/532 or 257/516) and capacitor and		
			ground with (plane or plate or film or		
Ι΄			layer)) or ((257/308 or 257/307 or		
ŀ			257/300) and capacitor and ground with		•
			(plane or plate or film or layer)) or		7,7
8			((257/298 or 257/691 or 257/E23.079 or		
ł			257/E23.153) and capacitor and ground with		
1 .	. 0.		(plane or plate or film or layer)))	1-10-1-10	

	315	(((semiconductor or die or chip or IC) and	USPAT;	2004/05/25 19:0
		capacitor and ground with (plane or plate	US-PGPUB;	
		or film or layer)) not (((257/787 or	EPO; JPO;	
•		257/724 or 257/723) and capacitor and	DERWENT;	
	1	ground with (plane or plate or film or	IBM TDB	
	1	layer)) or ((257/68 or 257/71 or 257/924)	TOP 1 DB	
	,			
		and capacitor and ground with (plane or		
		plate or film or layer)) or ((257/908 or		
		257/532 or 257/516) and capacitor and		<b>J</b> .
		ground with (plane or plate or film or		
		layer)) or ((257/308 or 257/307 or		
		257/300) and capacitor and ground with		1
	1	(plane or plate or film or layer)) or		
		((257/298 or 257/691 or 257/E23.079 or		
	1			0
	ŀ	257/E23.153) and capacitor and ground with		
		(plane or plate or film or layer)))) and	1	100
,		257/\$.ccls.		
	99	(((semiconductor or die or chip or IC) and	USPAT;	2004/05/25 20:0
		capacitor and ground with (plane or plate	US-PGPUB;	
		or film or layer)) not (((257/787 or	EPO; JPO;	
	1	257/724 or 257/723) and capacitor and	DERWENT;	·
	1	ground with (plane or plate or film or		
	Ι.		IBM_TDB	·
	1	and capacitor and ground with (plane or		
	1	plate or film or layer)) or ((257/908 or		2
	1	257/532 or 257/516) and capacitor and		
		ground with (plane or plate or film or		
	I	layer)) or ((257/308 or 257/307 or	1	
	1	257/300) and capacitor and ground with		
	,		1	
	,	(plane or plate or film or layer)) or		,
		((257/298 or 257/691 or 257/E23.079 or		. '
	1	257/E23.153) and capacitor and ground with	0	,
		(plane or plate or film or layer)))) and		
		decoupl\$3 with capacitor		
	69		USPAT;	2004/05/25 19:3
	·	and capacitor and ground with (plane or	US-PGPUB;	
		plate or film or layer)) not (((257/787 or	EPO; JPO;	
			1 / / / - / - / - / - / -	i
		1.257/724 or $257/723$ ) and canaditor and	DEBMENT.	
	:	257/724 or 257/723) and capacitor and	DERWENT;	
		ground with (plane or plate or film or	DERWENT; IBM_TDB	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924)	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924)	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl\$3 with capacitor) not	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and decoupl\$3 with capacitor) not ((((semiconductor or die or chip or IC)	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl\$3 with capacitor) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl\$3 with capacitor) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer))) not (((257/787 or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl\$3 with capacitor) not (((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer))) not (((257/787 or 257/724 or 257/723) and capacitor and	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl\$3 with capacitor) not (((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or plate or film or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and decoupl\$3 with capacitor) not (((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924)	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl\$3 with capacitor) not (((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or plate or film or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and decoupl\$3 with capacitor) not (((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and decoupl\$3 with capacitor) not (((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and decoupl\$3 with capacitor and ground with (plane or plate or film or layer))) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and decoupl\$3 with capacitor and ground with (plane or plate or film or layer)))) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or (1257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and decoupl\$3 with capacitor and ground with (plane or plate or film or layer)))) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl\$3 with capacitor and ground with (plane or plate or film or layer)))) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/508 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and decoupl\$3 with capacitor and ground with (plane or plate or film or layer)))) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl\$3 with capacitor and ground with (plane or plate or film or layer)))) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/508 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and decoupl\$3 with capacitor and ground with (plane or plate or film or layer))) and decoupl\$3 with capacitor) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or	1	
		ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer)))) and decoupl\$3 with capacitor and ground with (plane or plate or film or layer)))) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or (1257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or (1257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or (1257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or (1257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or (1257/308 or 257/307 or 257/300)	1	

-	2856	((((semiconductor or die or chip or IC)	USPAT;	2004/05/25 19:3
		and capacitor and ground with (plane or	US-PGPUB;	
		plate or film or layer)) not (((257/787 or	EPO; JPO;	
		257/724 or 257/723) and capacitor and	DERWENT;	
	1	ground with (plane or plate or film or	IBM_TDB	
		layer)) or ((257/68 or 257/71 or 257/924)		
		and capacitor and ground with (plane or		-
		plate or film or layer)) or ((257/908 or		K-
		257/532 or 257/516) and capacitor and	1	
	el B	ground with (plane or plate or film or		
		layer)) or ((257/308 or 257/307 or	*	
	4	257/300) and capacitor and ground with		
		(plane or plate or film or layer)) or		
		((257/298 or 257/691 or 257/E23.079 or		
		257/E23.153) and capacitor and ground with		
•				
		(plane or plate or film or layer)))) and		
		257/\$.ccls.) not ((((semiconductor or die	T.	
•	'	or chip or IC) and capacitor and ground		
		with (plane or plate or film or layer))	1	
	ŀ	not (((257/787 or 257/724 or 257/723) and		
	-	capacitor and ground with (plane or plate		
		or film or layer)) or ((257/68 or 257/71	8	
		or_257/924)_and capacitor_and_ground_with -		
		(plane or plate or film or layer)) or	1	
		((257/908 or 257/532 or 257/516) and	1	
		capacitor and ground with (plane or plate		
		or film or layer)) or ((257/308 or 257/307	-	· · · · · · · · · · · · · · · · · · ·
		or 257/300) and capacitor and ground with		
		(plane or plate or film or layer)) or	*	
		((257/298 or 257/691 or 257/E23.079 or		
		257/E23.153) and capacitor and ground with		
		(plane or plate or film or layer)))) and		
•		decoupl\$3 with capacitor)	1	
	1 1 2 2 2	((((semiconductor or die or chip or IC)	USPAT;	1 2004/05/25 10.2
	1332		ODITITI	2004/05/25-19:3
	1332	and capacitor and ground with (plane or	US-PGPUB;	2004/05/25:19:3
-	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or		2004/05/25:19:3
• .	1332	and capacitor and ground with (plane or	US-PGPUB;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or	US-PGPUB; EPO; JPO;	2004/05/25 19:3
•	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924)	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
19	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
,	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
· · · · · · · · · · · · · · · · · · ·	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
a)	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)))	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer))) not (((257/787 or 257/724 or 257/723) and	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer))	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or plate or film or layer)) not ((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not ((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and	US-PGPUB; EPO; JPO; DERWENT;	2004/03/23 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate	US-PGPUB; EPO; JPO; DERWENT;	2004/03/23 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307) or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or (257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or (257/298 or 257/691 or 257/E23.079 or	US-PGPUB; EPO; JPO; DERWENT;	2004/03/23 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/23.079 or 257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with	US-PGPUB; EPO; JPO; DERWENT;	2004/05/25 19:3
	1332	and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/68 or 257/71 or 257/924) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or 257/E23.153) and capacitor and ground with (plane or plate or film or layer))) and 257/\$.ccls.) not ((((semiconductor or die or chip or IC) and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or 257/724 or 257/723) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/908 or 257/532 or 257/516) and capacitor and ground with (plane or plate or film or layer)) or ((257/308 or 257/307 or 257/300) and capacitor and ground with (plane or plate or film or layer)) or ((257/298 or 257/691 or 257/E23.079 or (257/298 or 257/691 or 257/E23.079 or	US-PGPUB; EPO; JPO; DERWENT;	2004/03/23 19:3

	5457	(((semiconductor or die or chip or IC) and	USPAT;	2004/05/25 20:09
	0107	capacitor and ground with (plane or plate	US-PGPUB;	2004/03/23 20:03
		or film or layer)) not (((257/787 or	EPO; JPO;	
		257/724 or 257/723) and capacitor and		
	0		DERWENT;	
ļ		ground with (plane or plate or film or	IBM_TDB	•
		layer)) or ((257/68 or 257/71 or 257/924)	,	
		and capacitor and ground with (plane or		1
		plate or film or layer)) or ((257/908 or		
		257/532 or 257/516) and capacitor and		·
		ground with (plane or plate or film or		
		layer)) or ((257/308 or 257/307 or		
		257/300) and capacitor and ground with		
		(plane or plate or film or layer)) or		
		((257/298 or 257/691 or 257/E23.079 or		
		257/E23.153) and capacitor and ground with	<i>'</i>	·
	·	(plane or plate or film or layer)))) and		
		lead		
	4105	·		0004/05/05 00 00
	4125	((((semiconductor or die or chip or IC)	USPAT;	2004/05/25 20:09
		and capacitor and ground with (plane or	US-PGPUB;	
		plate or film or layer)) not (((257/787 or	EPO; JPO;	
		257/724 or 257/723) and capacitor and	DERWENT;	
		ground with (plane or plate or film or	IBM_TDB	
		layer)) or ((257/68 or 257/71 or 257/924)		
		and capacitor and ground with (plane or		
		plate or film or layer)) or ((257/908 or		
		257/532 or 257/516) and capacitor and		
		ground with (plane or plate or film or		
		layer)) or ((257/308 or 257/307 or	1	
		257/300) and capacitor and ground with		1
				1
		(plane or plate or film or layer)) or		
		((257/298 or 257/691 or 257/E23.079 or		·
		257/E23.153) and capacitor and ground with		
		(plane or plate or film or layer)))) and		
		lead) not ((((semiconductor or die or	<u> </u>	
		chip or IC) and capacitor and ground with		
ź		(plane or plate or film or layer)) not		
		(((257/787 or 257/724 or 257/723) and		
		capacitor and ground with (plane or plate	,	
		or film or layer)) or ((257/68 or 257/71		
		or 257/924) and capacitor and ground with		,
		(plane or plate or film or layer)) or		
		((257/908 or 257/532 or 257/516) and	•	
		capacitor and ground with (plane or plate	1	
		or film or layer)) or ((257/308 or 257/307	,	
		or 257/300) and capacitor and ground with		
		(plane or plate or film or layer)) or		
		((257/298 or 257/691 or 257/E23.079 or		
		257/E23.153) and capacitor and ground with	_	· ·
		(plane or plate or film or layer)))) and		
		257/\$.ccls.) not ((((semiconductor or die		
		or chip or IC) and capacitor and ground		
		with (plane or plate or film or layer))		
	,	not (((257/787 or 257/724 or 257/723) and		
	-			- ·
		capacitor and ground with (plane or plate		,
		or film or layer)) or ((257/68 or 257/71		· · ·
		or 257/924) and capacitor and ground with		
		(plane or plate or film or layer)) or		
		((257/908 or 257/532 or 257/516) and		
	-	capacitor and ground with (plane or plate		
		or film or layer)) or ((257/308 or 257/307		
		or 257/300) and capacitor and ground with		
		(plane or plate or film or layer)) or		
		((257/298 or 257/691 or 257/E23.079 or		
		257/E23.153) and capacitor and ground with		
		(plane or plate or film or layer)))) and	8	
	l .	decoupl\$3 with capacitor) and lead)	1	All and a second

-	200	(((((semiconductor or die or chip or IC)	USPAT;	1 2004 /05 /05	20.17
	1-	and capacitor and ground with (plane or		2004/05/25	20:12
		plate or film or layer)) not (((257/787 or	US-PGPUB;		
		257/724 or 257/723) and capacitor and	EPO; JPO;		
		ground with (plans and late of Sil	DERWENT;	İ	
		ground with (plane or plate or film or	IBM_TDB		
- 1		layer)) or ((257/68 or 257/71 or 257/924)			
		and capacitor and ground with (plane or	-		
1		plate or film or layer)) or ((257/908 or			
		257/532 or 257/516) and capacitor and	<u> </u>		
		ground with (plane or plate or film or	i		
		layer)) or ((257/308 or 257/307 or			
		257/300) and capacitor and ground with		ľ	
		(plane or plate or film or layer)) or			
		((257/298 or 257/691 or 257/E23.079 or			
		257/E23.153) and capacitor and ground with		_	
		(plane or plate or film or layer)))) and		- 30	
		lead) not (((((semiconductor or die or	,	0	
		Chip or IC) and conscitor and amount its			
		chip or IC) and capacitor and ground with	•		
		(plane or plate or film or layer)) not	, ·	•	
		(((257/787 or 257/724 or 257/723) and			
i		capacitor and ground with (plane or plate			
		or film or layer)) or ((257/68 or 257/71			
		or 257/924) and capacitor and ground with			
		(plane or plate or film or layer)) or			
		((257/908 or 257/532 or 257/516) and			
3		capacitor and ground with (plane or plate			
1		or film or layer)) or ((257/308 or 257/307		,	
		or 257/300) and capacitor and ground with			
		(plane or plate or film or layer)) or			
. [		((257/298 or 257/691 or 257/E23.079 or	•		
ĺ	-	257/E23.153) and capacitor and ground with			
		(plane or plate or film or layer)))) and			
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1		257/\$.ccls.) not ((((semiconductor or die			
		or chip or IC) and capacitor and ground			
		with (plane or plate or film or layer))			
		not (((257/787 or 257/724 or 257/723) and			
		capacitor and ground with (plane or plate			
		or film or layer)) or ((257/68 or 257/71			
,		or 257/924) and capacitor and ground with		45	
-	1	(plane or plate or film or layer)) or	•		
		((257/908 or 257/532 or 257/516) and	*		
1	}	capacitor and ground with (plane or plate			
İ	İ	or film or layer)) or ((257/308 or 257/307			
	l	or 257/300) and capacitor and ground with			
1		(plane or plate or film or layer)) or	9 .		
-	Ī	((257/298 or 257/691 or 257/E23.079 or			
	-	257/E23.153) and capacitor and ground with			
1		(plane or plate or film or lever)			
ľ	į	(plane or plate or film or layer)))) and			
1		decoup1\$3 with capacitor) and lead)) and			
	8	257/\$.ccls.			

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_	172	(((((semiconductor or die or chip or IC)	USPAT;	2004/05/25 20:17
		and capacitor and ground with (plane or	US-PGPUB;	
	*	plate or film or layer)) not (((257/787 or	EPO; JPO;	
	6	257/724 or 257/723) and capacitor and	DERWENT;	.,
		ground with (plane or plate or film or	IBM_TDB	
		layer)) or ((257/68 or 257/71 or 257/924)		× ×
		and capacitor and ground with (plane or		
		plate or film or layer)) or ((257/908 or		`
		257/532 or 257/516) and capacitor and		
		ground with (plane or plate or film or		(2)
		layer)) or ((257/308 or 257/307 or		
		257/300) and capacitor and ground with		
		(plane or plate or film or layer)) or		
		((257/298 or 257/691 or 257/E23.079 or		
		257/E23.153) and capacitor and ground with		
		(plane or plate or film or layer)))) and	,	·
-8-		lead) not (((((semiconductor or die or		
		chip or IC) and capacitor and ground with		,
		(plane or plate or film or layer)) not		
		(((257/787 or 257/724 or 257/723) and		
		capacitor and ground with (plane or plate		
		or film or layer)) or ((257/68 or 257/71	,	* *
		or 257/924) and capacitor and ground with		
		(plane or plate or film or layer)) or		
		((257/908 or 257/532 or 257/516) and		•
		capacitor and ground with (plane or plate		
		or film or layer)) or ((257/308 or 257/307		
		or 257/300) and capacitor and ground with		
	-	(plane or plate or film or layer)) or		
		((257/298 or 257/691 or 257/E23.079 or		
		257/E23.153) and capacitor and ground with		
,	*	(plane or plate or film or layer)))) and		
		257/\$.ccls.) not ((((semiconductor or die	Ì	·
		or chip or IC) and capacitor and ground		
		with (plane or plate or film or layer))		
		not (((257/787 or 257/724 or 257/723) and		
		capacitor and ground with (plane or plate		
		or film or layer)) or ((257/68 or 257/71		
		or 257/924) and capacitor and ground with	•	
61		(plane or plate or film or layer)) or		•
	·	((257/908 or 257/532 or 257/516) and		
*	1	capacitor and ground with (plane or plate		
		or film or layer)) or ((257/308 or 257/307		
		or 257/300) and capacitor and ground with		
		(plane or plate or film or layer)) or		, ,
		((257/298 or 257/691 or 257/E23.079 or		
	l	257/E23.153) and capacitor and ground with	7	,
	]	(plane or plate or film or layer)))) and		
	1	decoup1\$3 with capacitor) and lead)) and		
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	11 ((((semiconductor or die or chip or IC)	USPAT;	2004/05/25 20:2
	and capacitor and ground with (plane or	US-PGPUB;	
	plate or film or layer)) not (((257/787 or	EPO; JPO;	
	257/724 or 257/723) and capacitor and	DERWENT;	
	ground with (plane or plate or film or	IBM TDB	
	layer)) or ((257/68 or 257/71 or 257/924)	1011_100	
	and capacitor and ground with (plane or		-X-
	plate or film or layer)) or ((257/908 or		
	257/532 or 257/516) and capacitor and		
	ground with (plane or plate or film or		•
	layer)) or ((257/308 or 257/307 or		
	257/300) and capacitor and ground with		· ·
	(plane or plate or film or layer)) or		
	((257/298 or 257/691 or 257/E23.079 or		
	257/E23.153) and capacitor and ground with		
S	(plane or plate or film or layer)))) and		
	<pre>lead) not (((((semiconductor or die or</pre>		1
3	chip or IC) and capacitor and ground with		
	(plane or plate or film or layer)) not		
	(((257/787 or 257/724 or 257/723) and		
	capacitor and ground with (plane or plate	4	
	or film or layer)) or ((257/68 or 257/71		
	or 257/924) and capacitor and ground with -		
	(plane or plate or film or layer)) or		
	((257/908 or 257/532 or 257/516) and		1
,	capacitor and ground with (plane or plate		O.
	or film or layer)) or ((257/308 or 257/307		,
	or 257/300) and capacitor and ground with		
	(plane or plate or film or layer)) or		*
	((257/298 or 257/691 or 257/E23.079 or		
	257/E23.153) and capacitor and ground with	'	
	(plane or plate or film or layer)))) and		÷ .
-	257/\$.ccls.) not ((((semiconductor or die	*	-
0	or chip or IC) and capacitor and ground	* *	•
	with (plane or plate or film or layer))		
	not (((257/787 or 257/724 or 257/723) and	· 0	-
	capacitor and ground with (plane or plate		
	or film or layer)) or ((257/68 or 257/71		
'	or 257/924) and capacitor and ground with		
4	(plane or plate or film or layer)) or	·	6
	((257/908 or 257/532 or 257/516) and		
	capacitor and ground with (plane or plate		
4	or film or layer)) or ((257/308 or 257/307		
1	or 257/300) and capacitor and ground with		
	(plane or plate or film or layer)) or		
*	1		
	((257/298 or 257/691 or 257/E23.079 or		
	257/E23.153) and capacitor and ground with		

	192	((((semiconductor or die or chip or IC)	USPAT;	2004/05/25 20:2
		and capacitor and ground with (plane or	US-PGPUB;	
		plate or film or layer)) not (((257/787 or	EPO; JPO;	
		257/724 or 257/723) and capacitor and	DERWENT;	
		ground with (plane or plate or film or	IBM TDB	
		layer)) or ((257/68 or 257/71 or 257/924)	1211_100	
	-	and capacitor and ground with (plane or		
		plate or film or layer)) or ((257/908 or		
		257/532 or 257/516) and capacitor and		
	· .	ground with (plane or plate or film or		
	-	layer)) or ((257/308 or 257/307 or		
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		257/300) and capacitor and ground with		
		(plane or plate or film or layer)) or		
		((257/298 or 257/691 or 257/E23.079 or	ļ.	
		257/E23.153) and capacitor and ground with		
		(plane or plate or film or layer)))) and		
·	·	lead) not (((((semiconductor or die or		
		chip or IC) and capacitor and ground with	*	
		(plane or plate or film or layer)) not		
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		capacitor and ground with (plane or plate		or.
		or film or layer)) or ((257/68 or 257/71		·
		or 257/924) and capacitor and ground with		
		(plane or plate or film or layer)) or		
		((257/908 or 257/532 or 257/516) and		
	•	capacitor and ground with (plane or plate		
		or film or layer)) or ((257/308 or 257/307		
		or 257/300) and capacitor and ground with		
		(plane or plate or film or layer)) or	_	
		((257/298 or 257/691 or 257/E23.079 or		
	. "	257/E23.153) and capacitor and ground with		*
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		(plane or plate or film or layer)))) and		1
		257/\$.ccls.) not ((((semiconductor or die		
		or chip or IC) and capacitor and ground		
		with (plane or plate or film or layer))		
		not (((257/787 or 257/724 or 257/723) and		
		capacitor and ground with (plane or plate		
		or film or layer)) or ((257/68 or 257/71		ľ
	0.	or 257/924) and capacitor and ground with	*	
		(plane or plate or film or layer)) or		• *
1-		((257/908 or 257/532 or 257/516) and		
		capacitor and ground with (plane or plate		]
		or film or layer)) or ((257/308 or 257/307		
	0	or 257/300) and capacitor and ground with		
	į	(plane or plate or film or layer)) or		
,		((257/298 or 257/691 or 257/E23.079 or		
	1	257/E23.153) and capacitor and ground with	*	
		(plane or plate or film or layer)))) and		
		decoupl\$3 with capacitor) and lead)) and		
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162 (((((semiconductor or die or chip or IC) uspat; and capacitor and ground with (plane or plate or film or layer)) not (((257/787 or EPO; JPO;	- i /OO///OS/95 90.95
plate or film or layor) pot ((257/707)	2004/05/25 20:25
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ground with (plane or plate or film or IBM TDB	
layer)) or ((257/68 or 257/71 or 257/924)	
and capacitor and ground with (plane or	
plate or film or layer)) or ((257/908 or	
257/532 or 257/516) and capacitor and	1
ground with (plane or plate or film or	
layer)) or ((257/308 or 257/307 or	
257/300) and capacitor and ground with	
(plane or plate or film or laver)) or	
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257/E23.153) and capacitor and ground with	
(plane or plate or film or layer)))) and	1
lead) not (((((semiconductor or die or	*
chip or IC) and capacitor and ground with	
(plane or plate or film or layer)) not	
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or 257/924) and capacitor and ground with	ورسيفهم والمرافق والمستون والمجاهدة والمحاسر والما
(plane or plate or film or layer)) or	
((257/908 or 257/532 or 257/516) and	}
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or film or layer)) or ((257/308 or 257/307	•
or 257/300) and capacitor and ground with	
(plane or plate or film or layer)) or	
((257/298 or 257/691 or 257/E23.079 or	
257/E23.153) and capacitor and ground with	,
(plane or plate or film or layer)))) and	
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or chip or IC) and capacitor and ground	·
with (plane or plate or film or layer))	
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capacitor and ground with (plane or plate	
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or 257/924) and capacitor and ground with	• (X)
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or 257/300) and capacitor and ground with	+
(plane or plate or film or layer)) or	
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decoupl\$3 with capacitor) and lead)) and	
29/\$.ccls.	1